



BRIGHTTEK
BRIGHTTEK (EUROPE) LIMITED

Brighten Up The World With LED!



ISO/TS 16949:2009



BS EN ISO 14001:2004



QC 080000 IECQ HSPM

PRODUCT DATASHEET



- ▶ PCB / CHIP LED
- ▶ 0805 (2012) 0.8t
- ▶ Green (570nm)

NOG18S88



Release Date: 20 June 2017 Version: A1.0



0805 (2012) Series

RoHS
Compliant



FEATURES:

- **Package:** PCB / CHIP Top View SMT Package
- **Forward Current:** 20mA
- **Forward Voltage (typ.):** 1.9V
- **Luminous Intensity (typ.):** 10mcd@20mA
- **Colour:** Green
- **Wavelength:** 573nm
- **Viewing angle:** 140°
- **Materials:**
 - Die: GaP
 - Resin: Epoxy (Water Clear)
- **Operating Temperature:** -40~+85°C
- **Storage Temperature:** -40~+100°C
- **Electrostatics Discharge (ESD):** 2000V
- **Grouping parameters:**
 - Forward Voltage
 - Luminous Intensity
 - Dominant Wavelength
- **Soldering methods:** IR Reflow Soldering
- **Preconditioning:** MSL3 according to J-STD020
- **Packing:** 8mm tape with 4000/reel, ø180mm (7")

APPLICATIONS:

- Dashboard
- Indicator
- Switch Lights

CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
DC Forward Current	I_F	25	mA
Pulse Forward Current (Duty 1/10 @10KHz)	I_{PF}	120	mA
Reverse Current @5V	I_R	10	μ A
Power Dissipation	P_D	65	mW
Electrostatic Discharge (HBM)	ESD	2000	V
Operating Temperature	T_{OPR}	-40~+85	°C
Storage Temperature	T_{STG}	-40~+100	°C

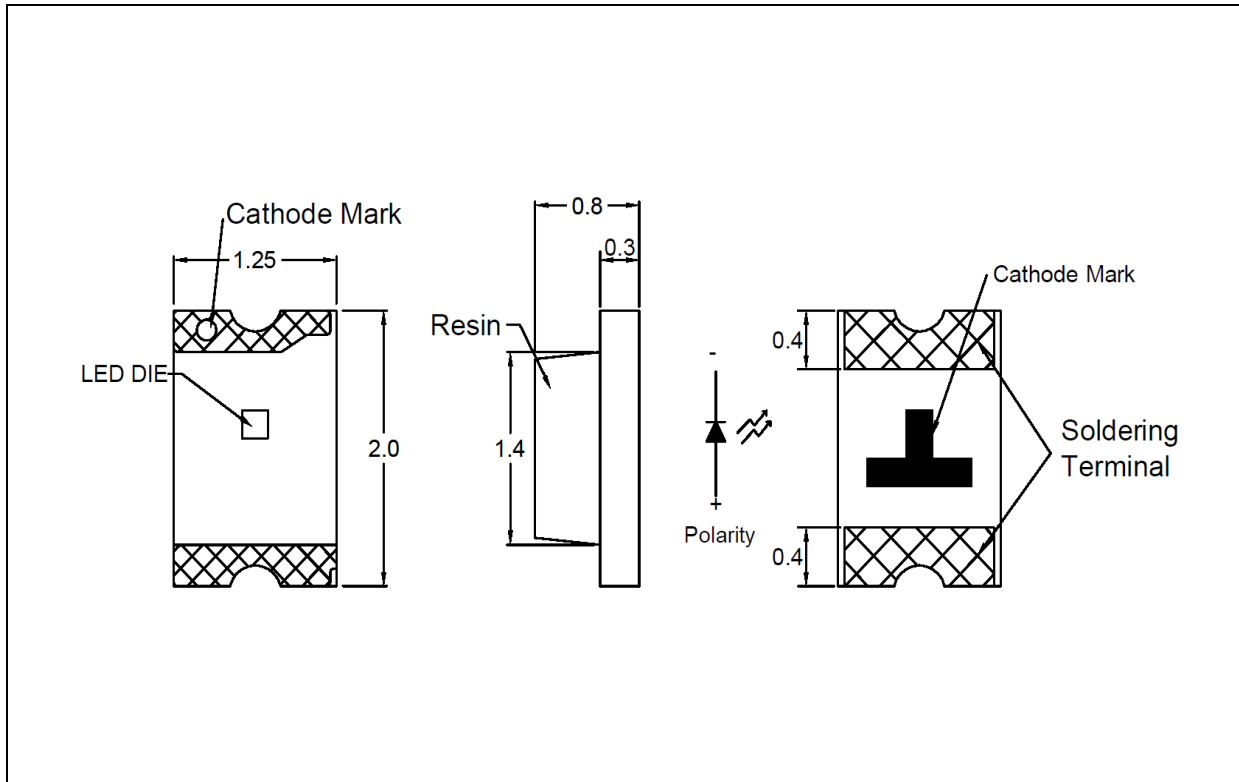
Electrical & Optical Characteristics (Ta=25°C)

Parameter	Symbol	Values			Unit	Test Condition
		Min.	Typ.	Max.		
Forward Voltage	V_F	1.5	1.9	2.4	V	$I_F=20mA$
Luminous Intensity	I_V	5	10	32	mcd	$I_F=20mA$
Dominant Wavelength	λ_D	566	573	576	nm	$I_F=20mA$
Spectral Line Half Bandwidth	$\Delta \lambda$	---	15	---	nm	$I_F=20mA$
Viewing Angle	$2\theta_{1/2}$	---	140	---	deg	$I_F=20mA$

- Luminous intensity (I_V) $\pm 15\%$, Forward Voltage (V_F) $\pm 0.1V$, Viewing angle($2\theta_{1/2}$) $\pm 10^\circ$

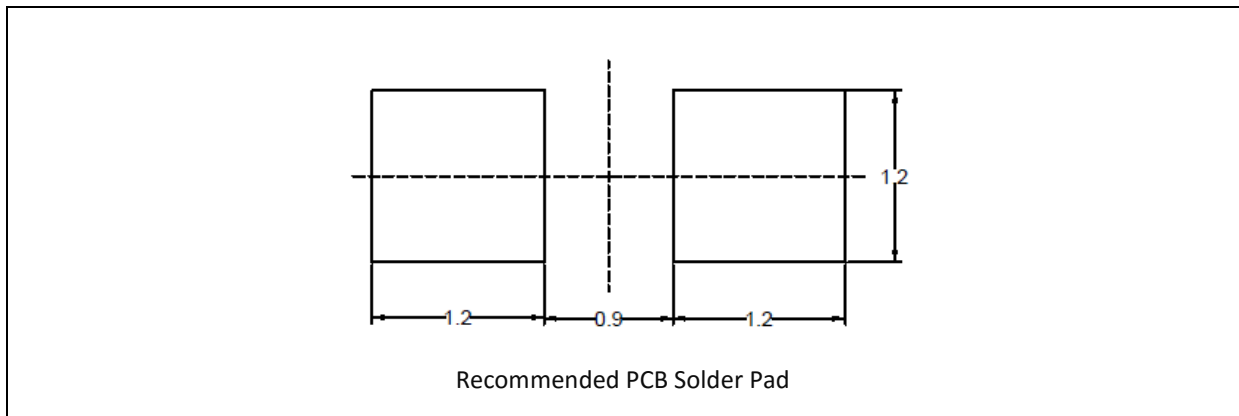
OUTLINE DIMENSION:

Package Dimension:



1. All dimensions are in millimetre (mm).
2. Tolerance $\pm 0.2\text{mm}$, unless otherwise noted.

Recommended Soldering Pad Dimension:



1. Dimensions are in millimetre (mm).
2. Tolerance $\pm 0.1\text{mm}$ with angle tolerance $\pm 0.5^\circ$.

BINNING GROUPS:

 Forward Voltage Classifications ($I_F = 20\text{mA}$):

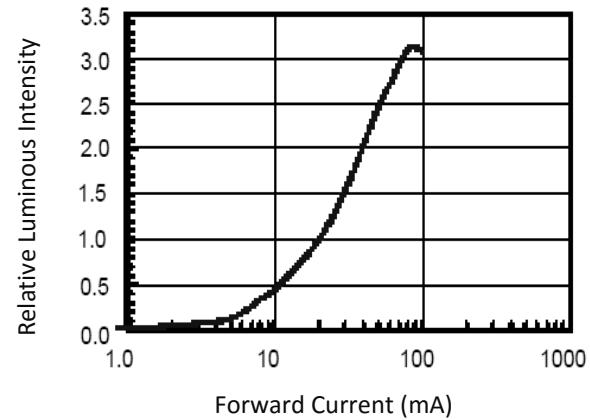
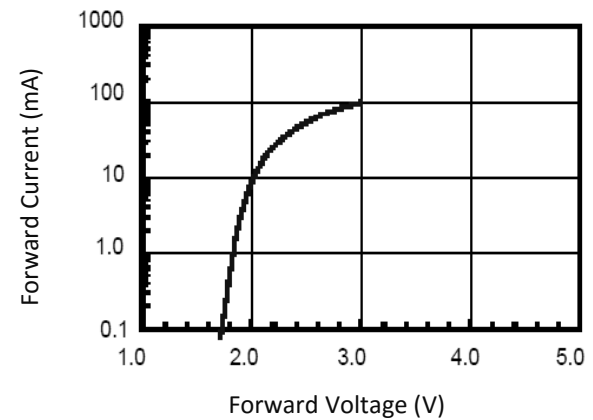
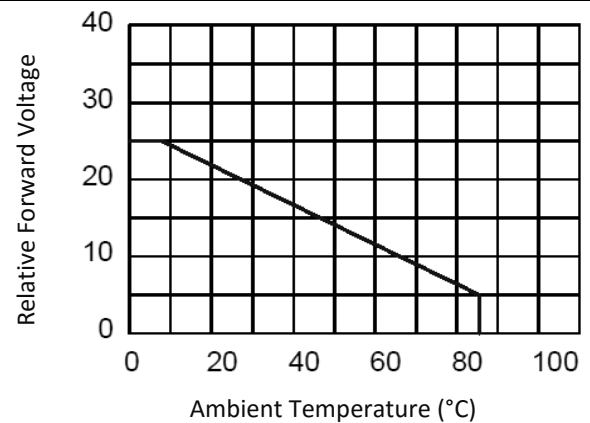
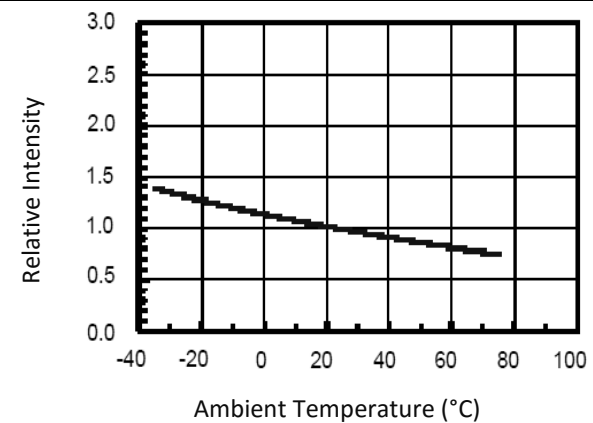
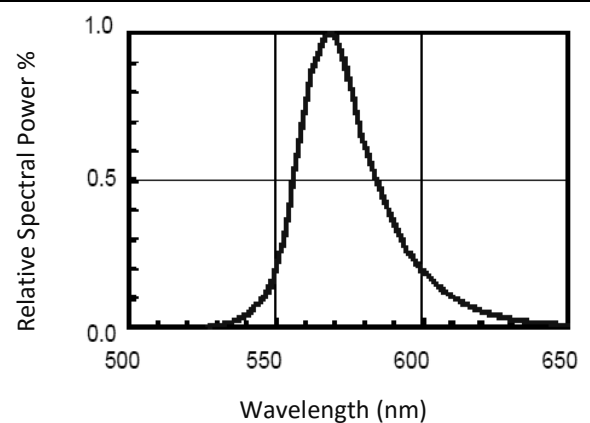
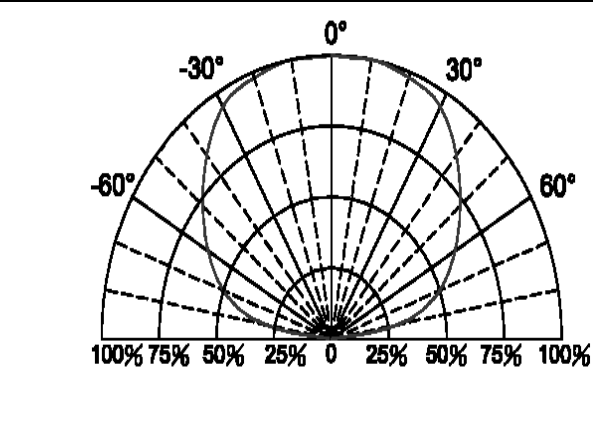
Code	Min.	Max.	Unit
1	1.5	2.4	V

 Luminous Intensity Classifications ($I_F = 20\text{mA}$):

Code	Min.	Max.	Unit
J	5	8	mcd
K	8	12.5	
L	12.5	20	
M	20	32	

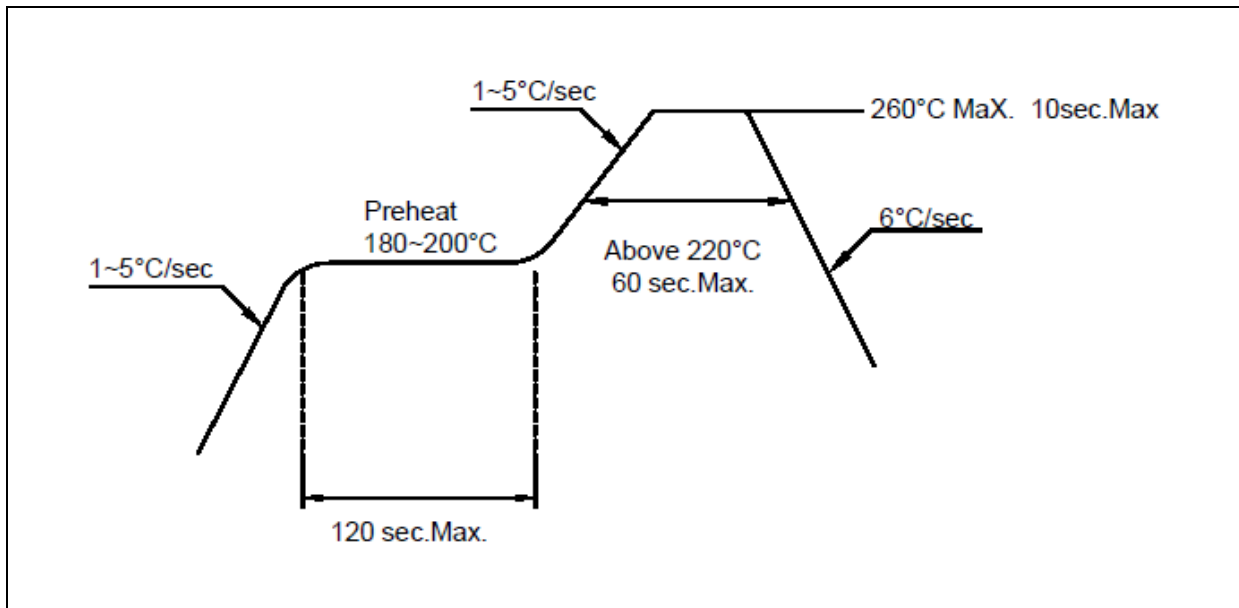
 Dominant Wavelength Classifications ($I_F = 20\text{mA}$):

Code	Min.	Max.	Unit
6	566	568	nm
7	568	570	
8	570	572	
9	572	574	
10	574	576	

ELECTRO-OPTICAL CHARACTERISTICS:
Relative Luminous Intensity v.s. Forward Current

Forward Current v.s. Forward Voltage

Relative Forward Voltage v.s. Ambient Temperature

Relative Intensity v.s. Ambient Temperature

Relative Spectral Power v.s. Wavelength

Directive Radiation


RECOMMENDED SOLDERING PROFILE:

Reflow Lead-free Solder:

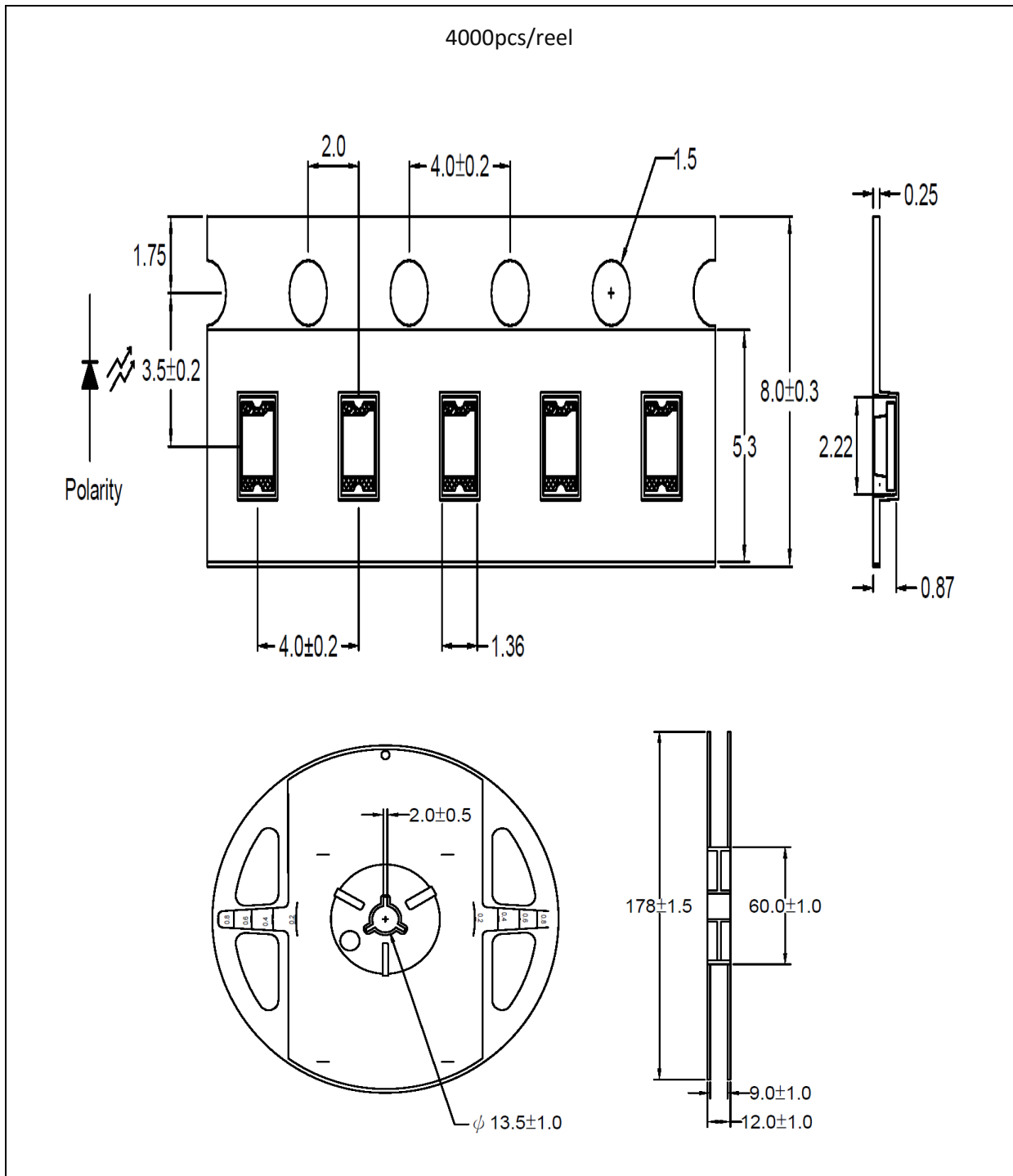


Note:

1. Maximum reflow soldering: 2 times.
2. Before, during, and after soldering, should not apply stress on the components and PCB board.

PACKING SPECIFICATION:

Reel Dimension:



PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 month at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with desiccating agent and apply baking at 60°C±5°C for 15hrs before use.

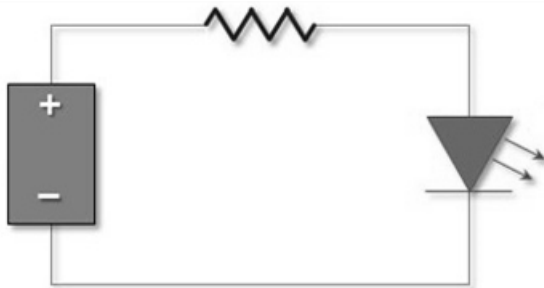
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

- 60±5°C x 15hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrostatic glove is recommended when handling the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.

REVISION RECORD:

Version	Date	Summary of Revision
A1.0	28/07/2015	Datasheet set-up.
A1.1	20/06/2017	Revise test condition.